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To the Director of the U.S. Patent and Tra

Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**

Byung-sun AHN

Execution Date(s) 12 January 2005

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

**3. Nature of conveyance:**

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

**2. Name and address of receiving party(ies)**

Name: Samsung Electronics Co., Ltd.

Internal Address:

Street Address: 416 Maetan-dong, Yeongtong-gu

City: Suwon-si, Gyeonggi-do

State:

Country: Republic of Korea

Zip:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

**4. Application or patent number(s):**

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Roylance, Abrams, Berdo & Goodman, L.L.P.

Internal Address:

Street Address: 1300 19th Street, N.W.

Suite 600

City: Washington

State: D.C.

Zip: 20036

Phone Number: (202) 659-9076

Fax Number: (202) 659-9344

Email Address:

**6. Total number of applications and patents involved:**

1

**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

- ☐ Authorized to be charged by credit card  
☐ Authorized to be charged to deposit account  
☒ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers  
Expiration Date

b. Deposit Account Number

Authorized User Name

**9. Signature:**

*Marcus R. Mickney*  
Signature

January 13, 2005

Date

Marcus R. Mickney

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

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**ASSIGNMENT**

WHEREAS, I, Byung-sun AHN, a citizen of the Republic of Korea, residing at 208-1004 Dongsuwon LG Village 2-Cha Apt., Mangpo-dong, Paldal-gu, Suwon-si, Gyeonggi-do, Republic of Korea (hereinafter ASSIGNOR), have made a certain invention entitled **PAPER ARRANGING APPARATUS AND ELECTROPHOTOGRAPHIC IMAGE FORMING APPARATUS INCLUDING THE SAME** for which I am making application for Letters Patent of the United States, said application being executed concurrently herewith; and

WHEREAS, Samsung Electronics Co., Ltd., a corporation duly organized under the laws of the Republic of Korea, located and doing business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (hereinafter ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention and the aforementioned application and any and all United States Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to me by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, by these presents do hereby sell, assign, set over and transfer unto said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States; and in, to and under the aforesaid United States application and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in the United States; and my right to file said applications and claim priority under the provisions of any international convention or treaty; and any Letters Patent of the United States issued or granted on said invention and/or said applications;

AND I HEREBY authorize and request the U.S. Patent and Trademark Office or other issuing authority to issue any and all patents on said invention and/or said application to said ASSIGNEE as sole assignee;

AND I HEREBY covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any assignment or other instrument in conflict herewith;

AND I HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns

to obtain and enforce proper patent protection on and for said invention in the United States, and likewise I make these provisions binding upon my heirs, legal representatives and/or administrators.

IN WITNESS WHEREOF, I have hereunder set my hand and seal this 12<sup>th</sup> day of January, 2005

  
Byung-sun AHN